

CS-02-073



October 6, 2003

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/616,268 07/09/03

Marvin Lo

ALUMINUM CAP WITH ELECTROLESS
NICKEL/IMMERSION GOLD

Grp. Art Unit:

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

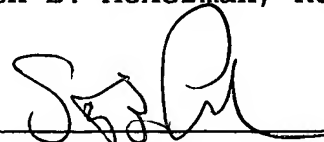
The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on October 10, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 10/10/03

CS-02-073

U.S. Patent 6,452,270 to Huang, "Semiconductor Device Having Bump Electrode," describes increased adhesion between the UBM and passivation by using a Ti UBM with a closed-loop shape.

U.S. Patent 6,521,996 to Seshan, "Ball Limiting Metallurgy for Input/Outputs and Methods of Fabrication," describes a lower adhesion layer that provides good adhesion to the passivation layer.

U.S. Patent 6,426,281 to Lin et al., "Method to Form Bump in Bumping Technology," describes a passivation layer that increases the adhesion to the UBM.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the typed name.

Stephen B. Ackerman,
Reg. No. 37761

